

Data sheet acquired from Harris Semiconductor SCHS242

CD74AC175, CD74ACT175

Quad D Flip-Flop with Reset

Features

September 1998

- · Buffered Inputs
- Typical Propagation Delay
- 6.4ns at $V_{CC} = 5V$, $T_A = 25^{\circ}C$, $C_L = 50pF$
- Exceeds 2kV ESD Protection MIL-STD-883, Method
- SCR-Latchup-Resistant CMOS Process and Circuit
- Speed of Bipolar FAST™/AS/S with Significantly **Reduced Power Consumption**
- Balanced Propagation Delays
- · AC Types Feature 1.5V to 5.5V Operation and Balanced Noise Immunity at 30% of the Supply
- ±24mA Output Drive Current
 - Fanout to 15 FAST™ ICs
 - Drives 50 Ω Transmission Lines

Description

The CD74AC175 and CD74ACT175 are guad D flip-flops with reset that utilize the Harris Advanced CMOS Logic technology. Information at the D input is transferred to the Q and Q outputs on the positive-going edge of the clock pulse. All four flip-flops are controlled by a common clock (CP) and a common reset (MR). Resetting is accomplished by a LOW logic level independent of the clock.

Ordering Information

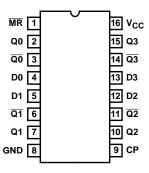
PART NUMBER	TEMP. RANGE (^O C)	PACKAGE	PKG. NO.
CD74AC175E	-55 to 125	16 Ld PDIP	E16.3
CD74ACT175E	-55 to 125	16 Ld PDIP	E16.3
CD74AC175M	-55 to 125	16 Ld SOIC	M16.15
CD74ACT175M	-55 to 125	16 Ld SOIC	M16.15

NOTES:

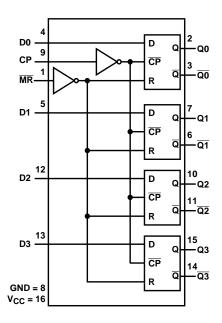
- 13. When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.
- 14. Wafer and die for this part number is available which meets all electrical specifications. Please contact your local sales office or Harris customer service for ordering information.

Pinout

CD74AC175, CD74ACT175 (PDIP, SOIC) **TOP VIEW**



Functional Diagram



TRUTH TABLE (EACH FLIP-FLOP)

	INPUTS	OUTPUTS			
RESET (MR)	CLOCK CP	DATA Dn	Qn	Qn	
L	Х	Х	L	Н	
Н	1	Н	Н	L	
Н	1	L	L	Н	
Н	L	Х	Q0	Q0	

= High Level (Steady State) = Low Level (Steady State)

= Irrelevant

↑ = Transition from Low to High level
Q0, Q0 = Level before the Indicated Steady-State Input conditions were established.

 θ_{JA} (°C/W)

90

160

..150^oC

Absolute Maximum Ratings Thermal Information DC Supply Voltage, V_{CC} -0.5V to 6V Thermal Resistance (Typical, Note 5) DC Input Diode Current, I_{IK} For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$ ± 20 mA SOIC Package..... DC Output Diode Current, IOK Maximum Junction Temperature (Plastic Package) Maximum Storage Temperature Range-65°C to 150°C DC Output Source or Sink Current per Output Pin, IO Maximum Lead Temperature (Soldering 10s).....300°C (SOIC - Lead Tips Only) DC V_{CC} or Ground Current, I_{CC or} I_{GND} (Note 3) ±100mA **Operating Conditions** Temperature Range, T_A -55°C to 125°C Supply Voltage Range, V_{CC} (Note 4) AC Types......1.5V to 5.5V DC Input or Output Voltage, $\text{V}_{\text{I}},\,\text{V}_{\text{O}}\,\ldots\ldots\ldots$ 0V to V_{CC} Input Rise and Fall Slew Rate, dt/dv AC Types, 1.5V to 3V 50ns (Max)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

- 15. For up to 4 outputs per device, add ±25mA for each additional output.
- 16. Unless otherwise specified, all voltages are referenced to ground.

AC Types, 3.6V to 5.5V 20ns (Max)

17. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

DC Electrical Specifications

			ST ITIONS	V _{CC} 25°C		-40°C TO 25°C 85°C		-55°C TO 125°C			
PARAMETER	SYMBOL	V _I (V)	I _O (mA)	(V)	MIN	MAX	MIN	MAX	MIN	MAX	UNITS
AC TYPES		-					-	-	-	-	
High Level Input Voltage	V _{IH}	-	-	1.5	1.2	-	1.2	-	1.2	-	V
				3	2.1	-	2.1	-	2.1	-	V
				5.5	3.85	-	3.85	-	3.85	-	V
Low Level Input Voltage	V_{IL}	-	-	1.5	-	0.3	-	0.3	-	0.3	V
				3	-	0.9	-	0.9	-	0.9	V
				5.5	-	1.65	-	1.65	-	1.65	V
High Level Output Voltage	V _{ОН}	V _{IH} or V _{IL}	-0.05	1.5	1.4	-	1.4	-	1.4	-	V
			-0.05	3	2.9	-	2.9	-	2.9	-	V
			-0.05	4.5	4.4	-	4.4	-	4.4	-	V
			-4	3	2.58	-	2.48	-	2.4	-	V
			-24	4.5	3.94	-	3.8	-	3.7	-	V
			-75 (Note 6, 7)	5.5	-	-	3.85	-	-	-	V
			-50 (Note 6, 7)	5.5	-	-	-	-	3.85	-	V

DC Electrical Specifications (Continued)

		TEST CONDITIONS		v _{cc}	25°C		-40°C TO 85°C		-55°C TO 125°C		
PARAMETER	SYMBOL	V _I (V)	I _O (mA)	(V)	MIN	MAX	MIN	MAX	MIN	MAX	UNITS
Low Level Output Voltage	V_{OL}	V _{IH} or V _{IL}	0.05	1.5	-	0.1	-	0.1	-	0.1	V
			0.05	3	-	0.1	-	0.1	-	0.1	V
			0.05	4.5	-	0.1	-	0.1	-	0.1	V
			12	3	-	0.36	-	0.44	-	0.5	V
			24	4.5	-	0.36	-	0.44	-	0.5	V
			75 (Note 6, 7)	5.5	-	-	-	1.65	-	-	V
			50 (Note 6, 7)	5.5	-	-	-	-	-	1.65	V
Input Leakage Current	lį	V _{CC} or GND	-	5.5	-	±0.1	-	±1	-	±1	μА
Quiescent Supply Current MSI	I _{CC}	V _{CC} or GND	0	5.5	-	8	-	80	-	160	μΑ
ACT TYPES											
High Level Input Voltage	V _{IH}	-	-	4.5 to 5.5	2	-	2	-	2	-	V
Low Level Input Voltage	V _{IL}	-	-	4.5 to 5.5	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage	V _{OH}	V _{IH} or V _{IL}	-0.05	4.5	4.4	-	4.4	-	4.4	-	V
			-24	4.5	3.94	-	3.8	-	3.7	-	V
			-75 (Note 6, 7)	5.5	-	-	3.85	-	-	-	V
			-50 (Note 6, 7)	5.5	-	-	-	-	3.85	-	V
Low Level Output Voltage	V _{OL}	V _{IH} or V _{IL}	0.05	4.5	-	0.1	-	0.1	-	0.1	V
			24	4.5	-	0.36	-	0.44	-	0.5	V
			75 (Note 6, 7)	5.5	-	-	-	1.65	-	-	V
			50 (Note 6, 7)	5.5	-	-	-	-	-	1.65	V
Input Leakage Current	lį	V _{CC} or GND	-	5.5	-	±0.1	-	±1	-	±1	μА
Quiescent Supply Current MSI	Icc	V _{CC} or GND	0	5.5	-	8	-	80	-	160	μА
Additional Supply Current per Input Pin TTL Inputs High 1 Unit Load	Δl _{CC}	V _{CC} -2.1	-	4.5 to 5.5	-	2.4	-	2.8	-	3	mA

NOTES:

ACT Input Load Table

INPUT	UNIT LOAD
Dn	0.58
MR	0.67
СР	0.92

NOTE: Unit load is ΔI_{CC} limit specified in DC Electrical Specifications Table, e.g., 2.4mA max at 25°C.

^{18.} Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

^{19.} Test verifies a minimum 50Ω transmission-line-drive capability at 85^{o} C, 75Ω at 125^{o} C.

Prerequisite For Switching Function

			-40°C TO 85°C		-55°C T		
PARAMETER	SYMBOL	V _{CC} (V)	MIN	MAX	MIN	MAX	UNITS
AC TYPES							
Data to CP Set-Up Time	t _{SU}	1.5	2	-	2	-	ns
		3.3 (Note 8)	2	-	2	-	ns
		5 (Note 9)	2	-	2	-	ns
Hold Time	t _H	1.5	2	-	2	-	ns
		3.3	2	-	2	-	ns
		5	2	-	2	-	ns
Removal Time, MR to CP	t _{REM}	1.5	1	-	1	-	ns
		3.3	1	-	1	-	ns
		5	1	-	1	-	ns
MR Pulse Width	t _W	1.5	44	-	50	-	ns
		3.3	4.9	-	5.6	-	ns
		5	3.5	-	4	-	ns
CP Pulse Width	t _W	1.5	55	-	63	-	ns
		3.3	6.1	-	7	-	ns
		5	4.4	-	5	-	ns
CP Frequency	f _{MAX}	1.5	9	-	8	-	MHz
		3.3	81	-	71	-	MHz
		5	114	-	100	-	MHz
ACT TYPES	•		•	•	•	•	•
Data to CP Set-Up Time	tsu	5 (Note 9)	2	-	2	-	ns
Hold Time	t _H	5	2	-	2	-	ns
Removal Time, MR to CP	t _{REM}	5	1	-	1	-	ns
MR Pulse Width	t _W	5	3.5	-	4	-	ns
Clock Pulse Width	t _W	5	4.4	-	5	-	ns
CP Frequency	f _{MAX}	5	114	-	114	-	MHz

NOTES:

20. 3.3V Min is at 3V.

21. 5V Min is at 4.5V.

Switching Specifications Input t_r , t_f = 3ns, C_L = 50pF (Worst Case)

			-40°C TO 85°C		-55°C TO 125°C				
PARAMETER	SYMBOL	V _{CC} (V)	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
AC TYPES									
Propagation Delay, CP to Q, Q	t _{PLH} , t _{PHL}	1.5	-	-	139	-	-	153	ns
		3.3 (Note 11)	4.4	-	15.5	4.3	-	17.1	ns
		5 (Note 12)	3.2	-	11.1	3.1	1	12.2	ns

Switching Specifications Input t_r , $t_f = 3ns$, $C_L = 50pF$ (Worst Case) (Continued)

			-40°C TO 85°C		-55°C TO 125°C				
PARAMETER	SYMBOL	V _{CC} (V)	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
Propagation Delay, MR to Q, Q	t _{PLH} , t _{PHL}	1.5	-	-	139	-	-	153	ns
		3.3	4.4	-	15.5	4.3	-	17.1	ns
		5	3.2	-	11.1	3.1	-	12.2	ns
Input Capacitance	C _I	-	-	-	10	-	-	10	pF
Power Dissipation Capacitance	C _{PD} (Note 13)	-	-	55	-	-	55	-	pF
ACT TYPES					•		•		•
Propagation Delay, CP to Qn	t _{PLH} , t _{PHL}	5 (Note 12)	3	-	10.5	2.9	-	11.5	ns
Propagation Delay, MR to Qn	t _{PLH} , t _{PHL}	5	3.3	-	11.8	3.3	-	13	ns
Input Capacitance	Cl	-	-	-	10	-	-	10	pF
Power Dissipation Capacitance	C _{PD} (Note 13)	-	-	55	-	-	55	-	pF

NOTES:

22. Limits tested 100%.

INPUT LEVEL

INPUT LEVEL

GND

- 23. 3.3V Min is at 3.6V, Max is at 3V.
- 24. 5V Min is at 5.5V, Max is at 4.5V.
- 25. C_{PD} is used to determine the dynamic power consumption per flip-flop. $P_D = C_{PD} \ V_{CC}^2 \ f_i + \Sigma \ (C_L + V_{CC}^2 \ f_0) + V_{CC} \ \Delta I_{CC}$ where f_i = input frequency, f_0 = output frequency, C_L = output load capacitance, V_{CC} = supply voltage.

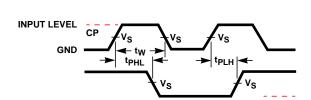


FIGURE 5. PROPAGATION DELAYS

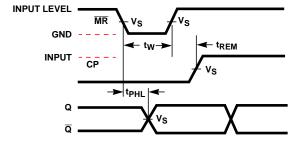
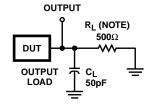


FIGURE 6. RESET OR SET PREREQUISITE AND PROPAGATION DELAYS



NOTE: For AC Series Only: When $\rm V_{CC}$ = 1.5V, $\rm R_{L}$ = 1k $\Omega.$

	CD74AC	CD74ACT
Input Level	V _{CC}	3V
Input Switching Voltage, V _S	0.5 V _{CC}	1.5V
Output Switching Voltage, V _S	0.5 V _{CC}	0.5 V _{CC}

FIGURE 7.

 $t_{SU}(L)$

t_H(L)

 $t_{SU}(H)$

FIGURE 8. PROPAGATION DELAY TIMES

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